

Progress Report:

Effect of Helium and Deuterium Implantation on Tungsten Surfaces at $T > 1000$ °C

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Overview

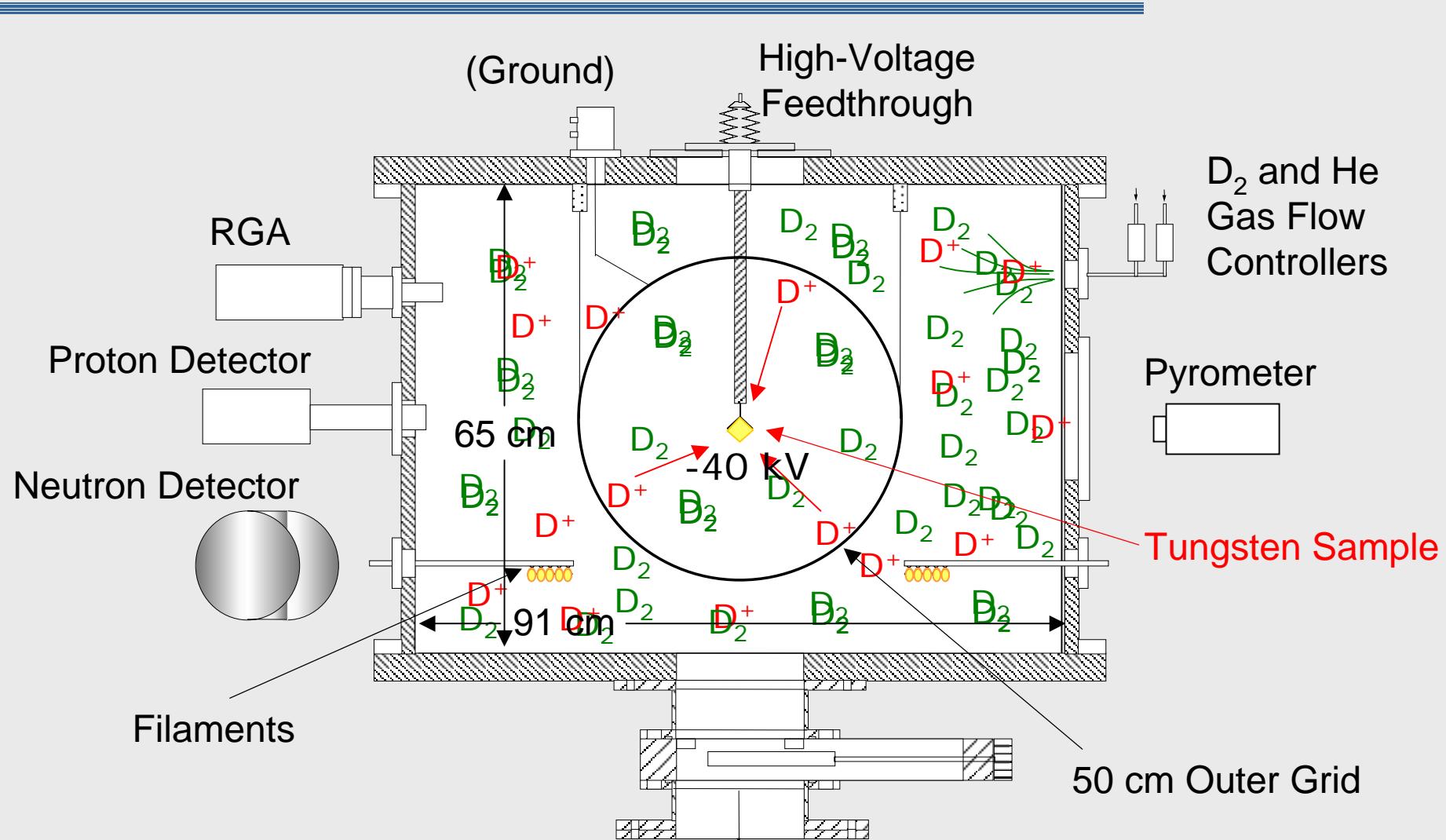
■ Objective

Determine the effects of high energy deuterium & helium implantation on tungsten surfaces at temperatures > 1000 °C

■ Outline

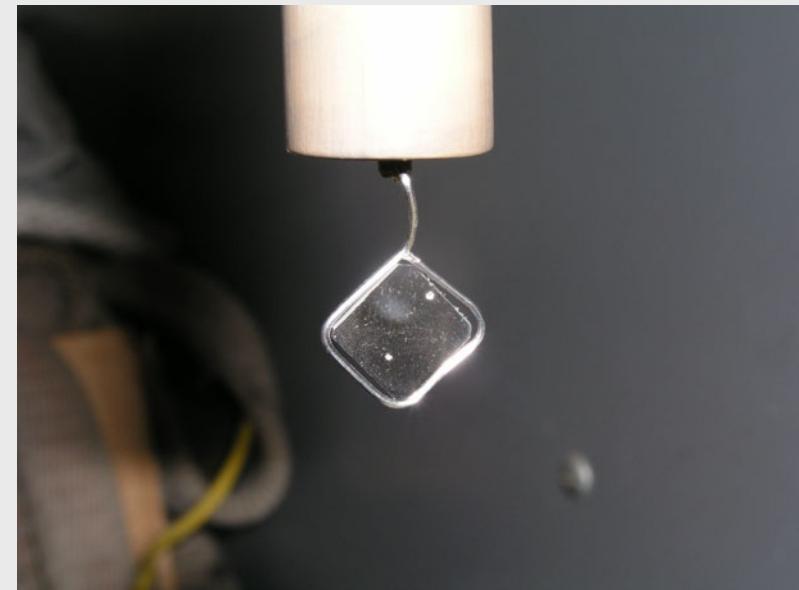
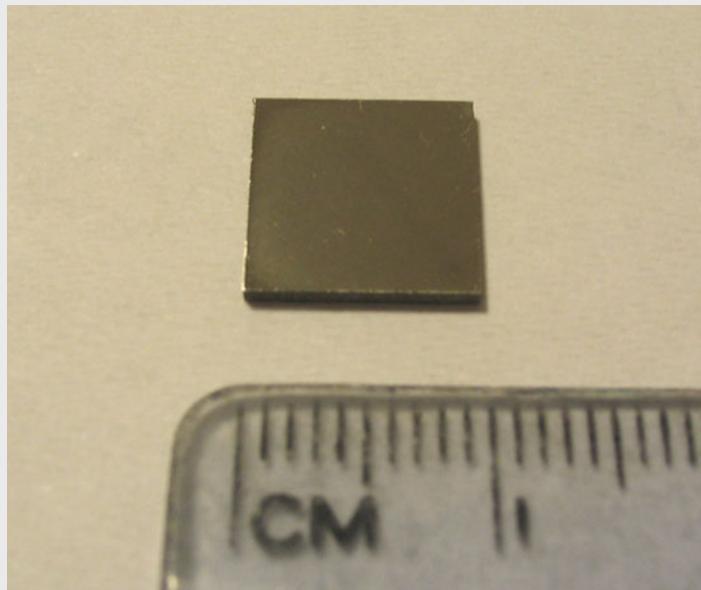
- Experimental Setup
- Sample Characteristics
- Deuterium and Helium Results
- Discussion
- Future Work

IEC Chamber Used for Ion Implantation

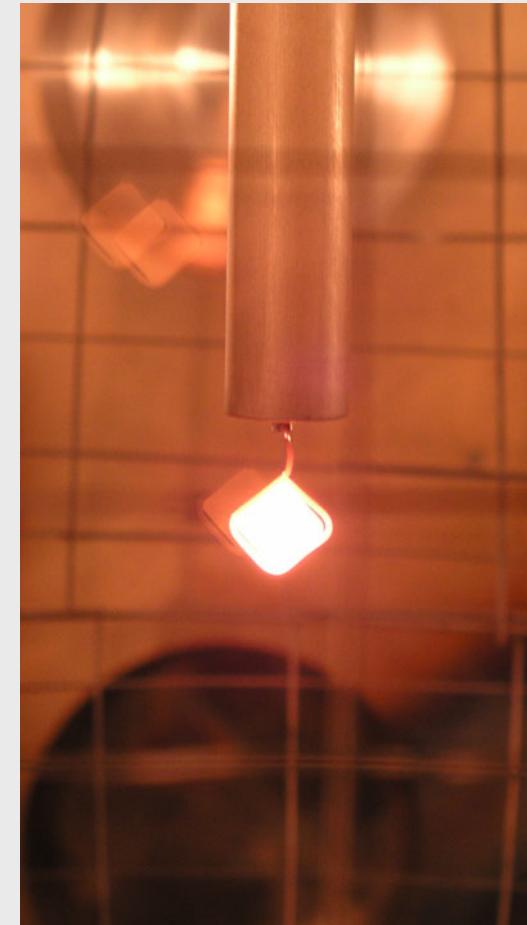
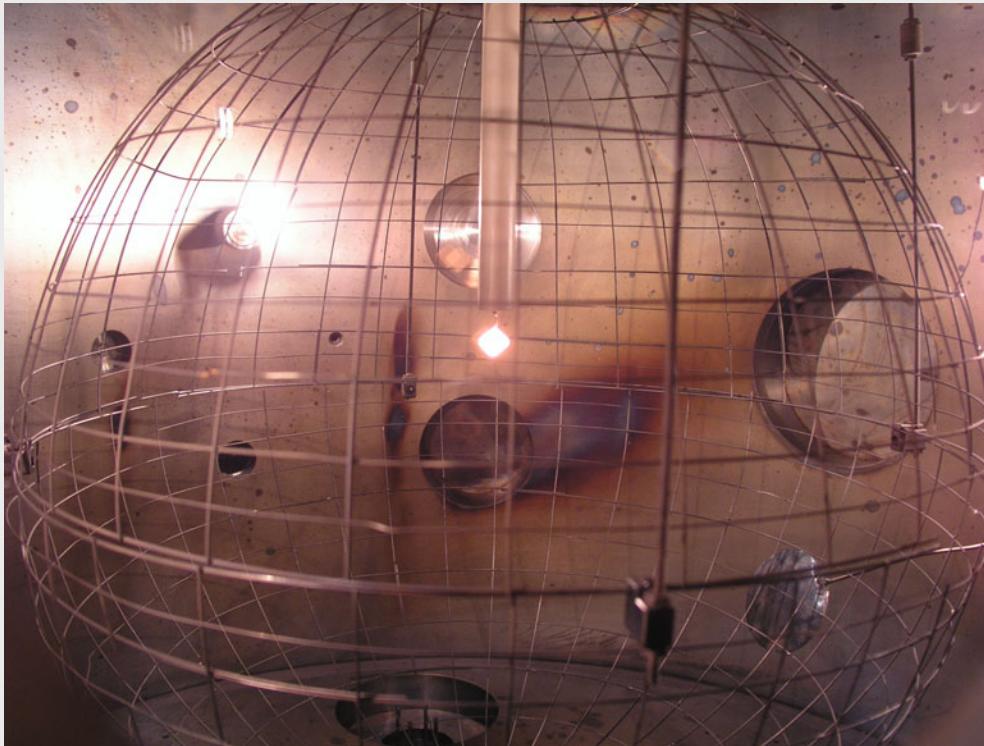


Tungsten Samples

- Powder metallurgy samples
- Obtained from Lance Snead, Oak Ridge
- Polished finish
- Lot #F05M12, stock #13981
- Spot-welded on to a W-Re wire loop



UW IEC Chamber has Capability of High-Temperature Implantation at 10-150 kV



D⁺, 20 kV, 5 mA
2 mtorr, 1100 °C

Conditions for Implantation of First Four Samples



Sample	Temperature	Deuterium	Helium
1	1100 °C 30 min	-	-
2	1000-1300 °C 32 min	$2 \times 10^{19} \text{ cm}^{-2}$ 20-40 kV	-
3	1100 °C 2 min	-	$6 \times 10^{17} \text{ cm}^{-2}$ 40 kV
4	1200 °C 10 min	-	$6 \times 10^{18} \text{ cm}^{-2}$ 40 kV

Heating Tungsten Sample to 1100 °C Caused Grain Growth



Tungsten Powder Met.
As Received

Tungsten Powder Met.
1100 °C for 30 min.
Non-Irradiated
(Sample 1)

5 μm

5 μm

Deuterium Did Not Cause Blistering But Caused Substantial Grain Growth



Tungsten Powder Met.
As Received

25 μm

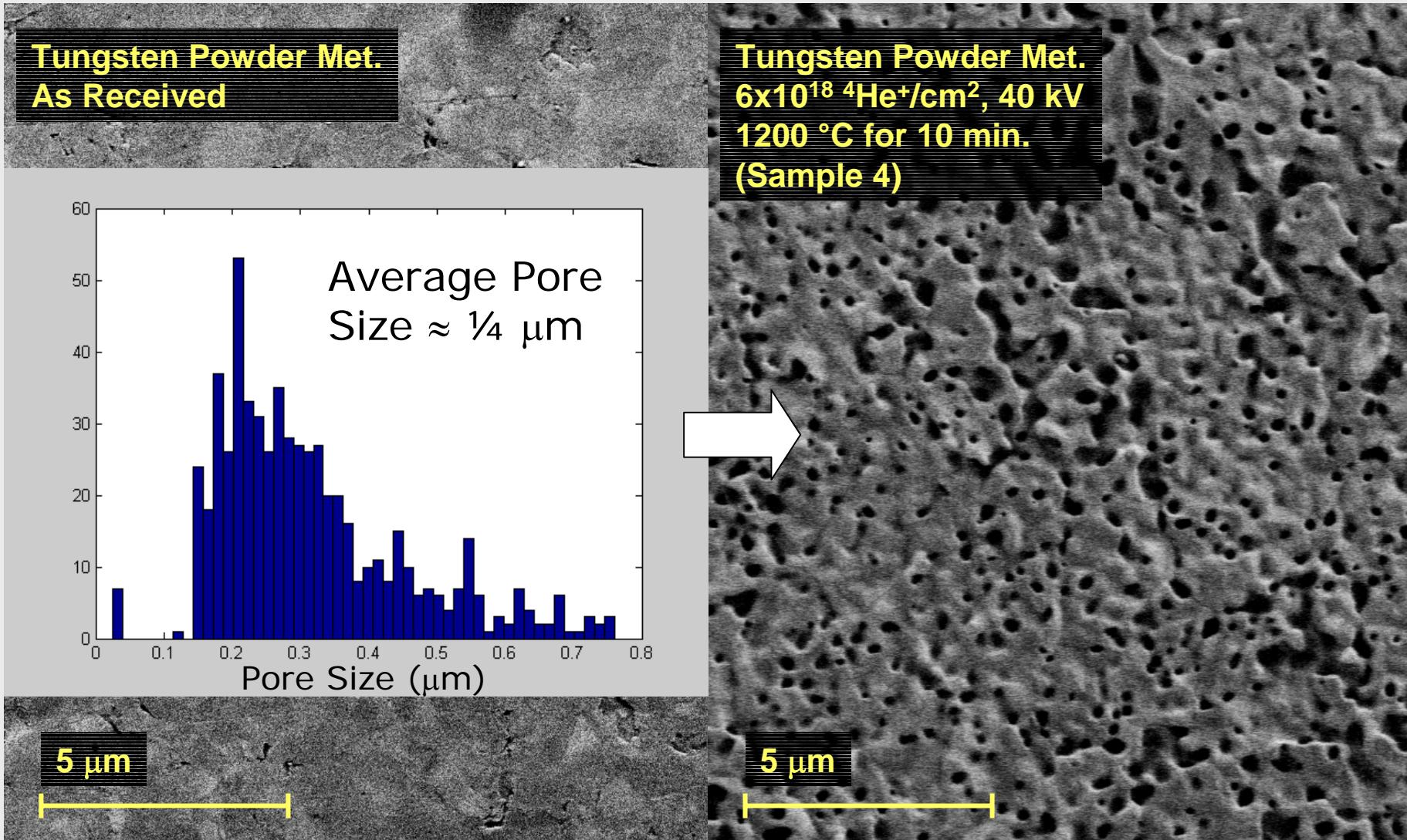


Tungsten Powder Met.
 $2 \times 10^{19} \text{ D}^+/\text{cm}^2$, 20-40 kV
1000-1300 °C for 32 min.
(Sample 2)

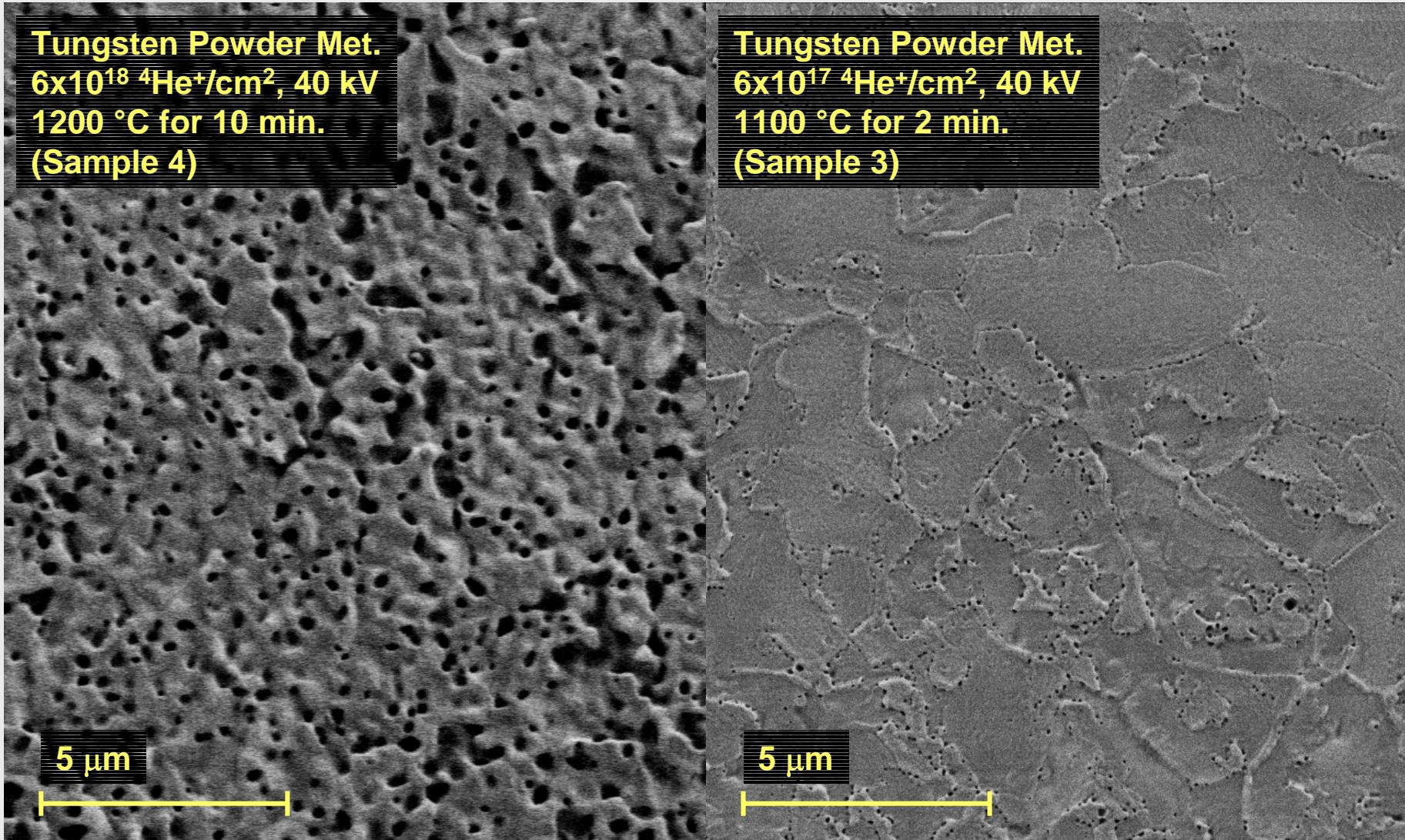
25 μm



High Temp. Helium Implantation at 6×10^{18} $^4\text{He}^+/\text{cm}^2$ Created Porous Surface Structure



Pores Decorate Grain Boundaries at Lower Ion Fluence ($6 \times 10^{17} \text{ }^4\text{He}^+/\text{cm}^2$)

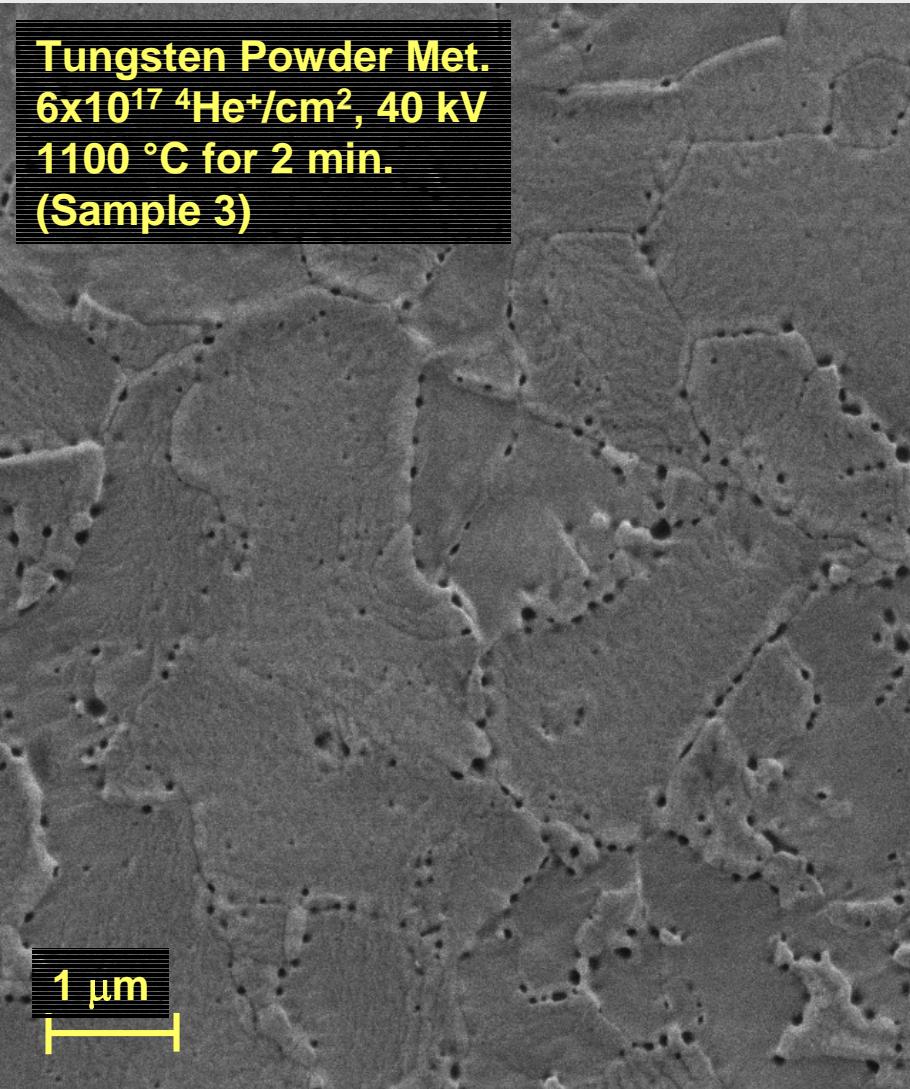
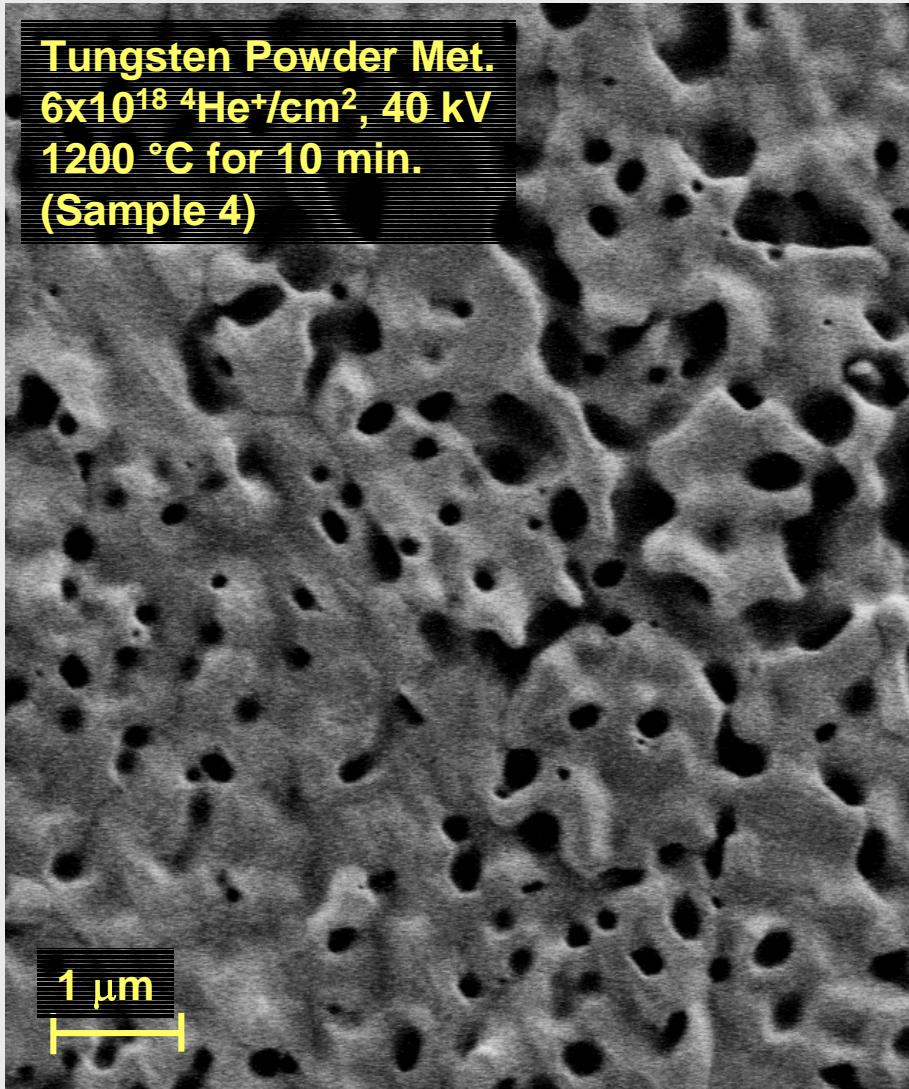


Pores Decorate Grain Boundaries at Lower Ion Fluence ($6 \times 10^{17} \text{ }^4\text{He}^+/\text{cm}^2$)

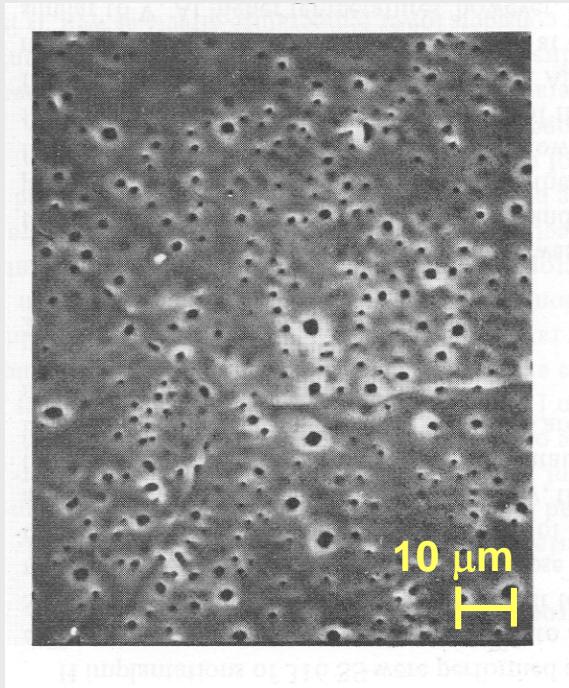


Tungsten Powder Met.
 $6 \times 10^{18} \text{ }^4\text{He}^+/\text{cm}^2$, 40 kV
1200 °C for 10 min.
(Sample 4)

Tungsten Powder Met.
 $6 \times 10^{17} \text{ }^4\text{He}^+/\text{cm}^2$, 40 kV
1100 °C for 2 min.
(Sample 3)



Pinhole Structure Seen 30 Years Ago



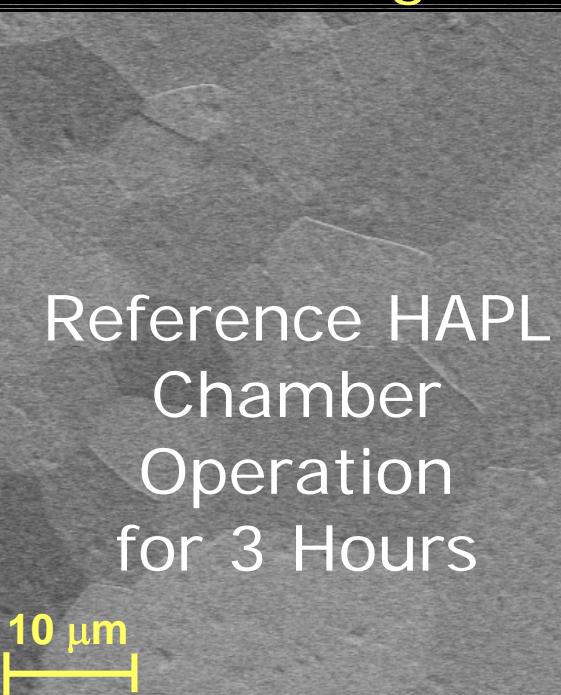
Vanadium @ 1200 °C
300 keV He⁺ 2×10^{18} ions/cm²

- “Pinhole” structure shown by the work of Thomas and Bauer on Vanadium (1974)
- Authors’ Conclusions:
 - At high temperatures, bubbles intersect the surface to form the porous structure
 - This porous structure is stable and results in 100% helium re-emission

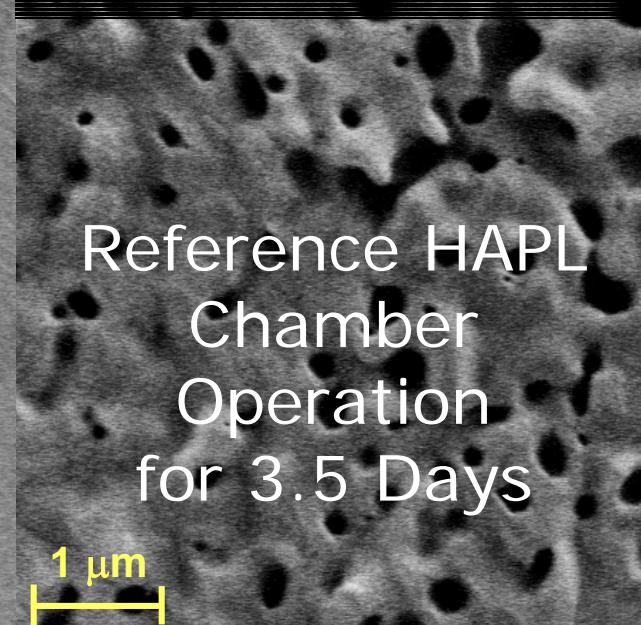
G.J. Thomas & W. Bauer, *J. Nucl. Mater.* (1974) 53, 134.

Preliminary Conclusions

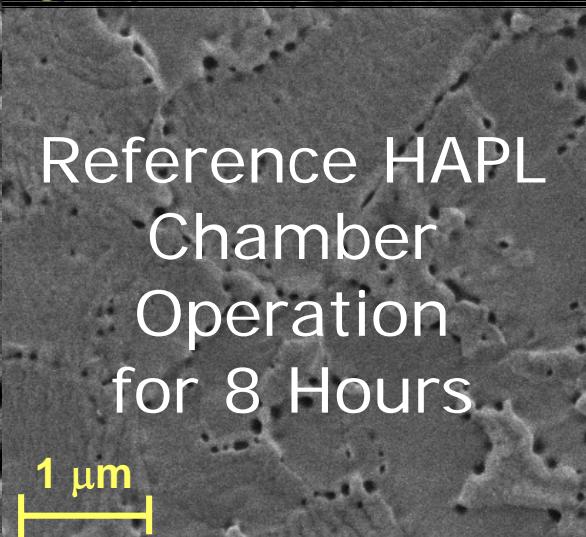
At 1100-1300 °C,
 2×10^{19} D⁺/cm²
implantation
produced no
blistering



At 1200 °C,
 6×10^{18} He⁺/cm²
implantation
produced
“pinhole” porous
surface structure



At 1100 °C,
 6×10^{17} He⁺/cm²
implantation
produced helium
bubbles that
decorate the
grain boundaries

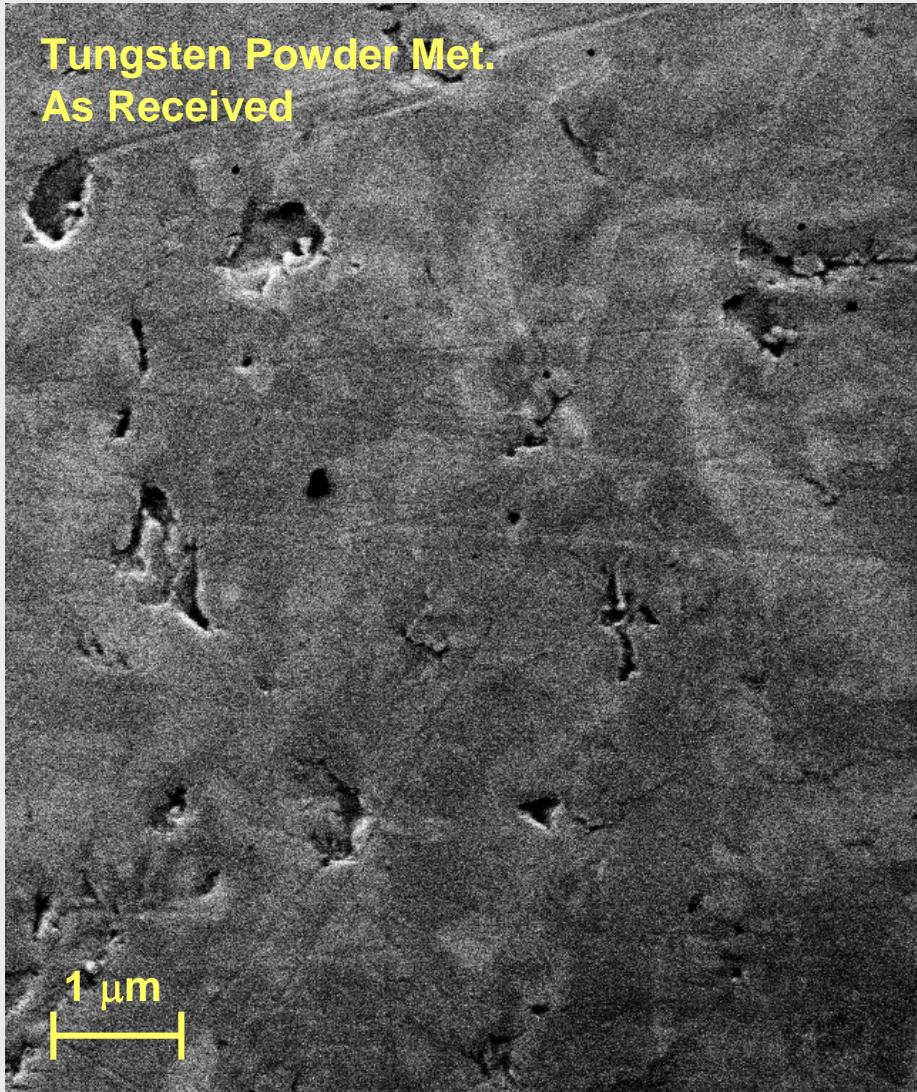


Future Work

- Higher Energy Implantation (40-100 kV)
- Implantation at Different Flux Levels
- Implantation at Different Temperatures
- Simultaneous D and ${}^4\text{He}$ Implantation
- Ion Density Depth Distribution

Deuterium Did Not Cause Blistering But Caused Substantial Grain Growth

Tungsten Powder Met.
As Received



Tungsten Powder Met.
 $2 \times 10^{19} D^+/\text{cm}^2$, 20-40 kV
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